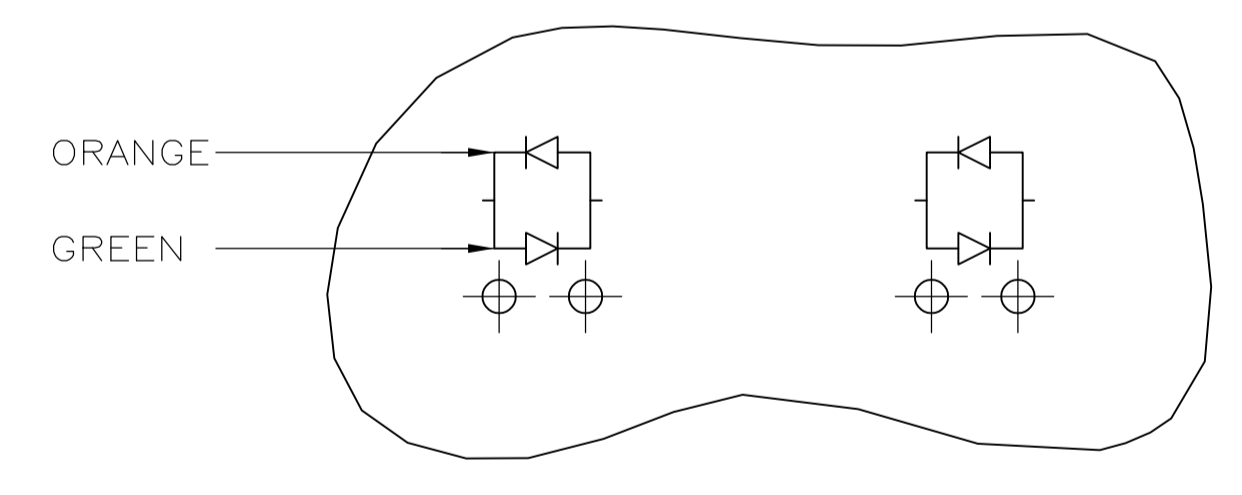
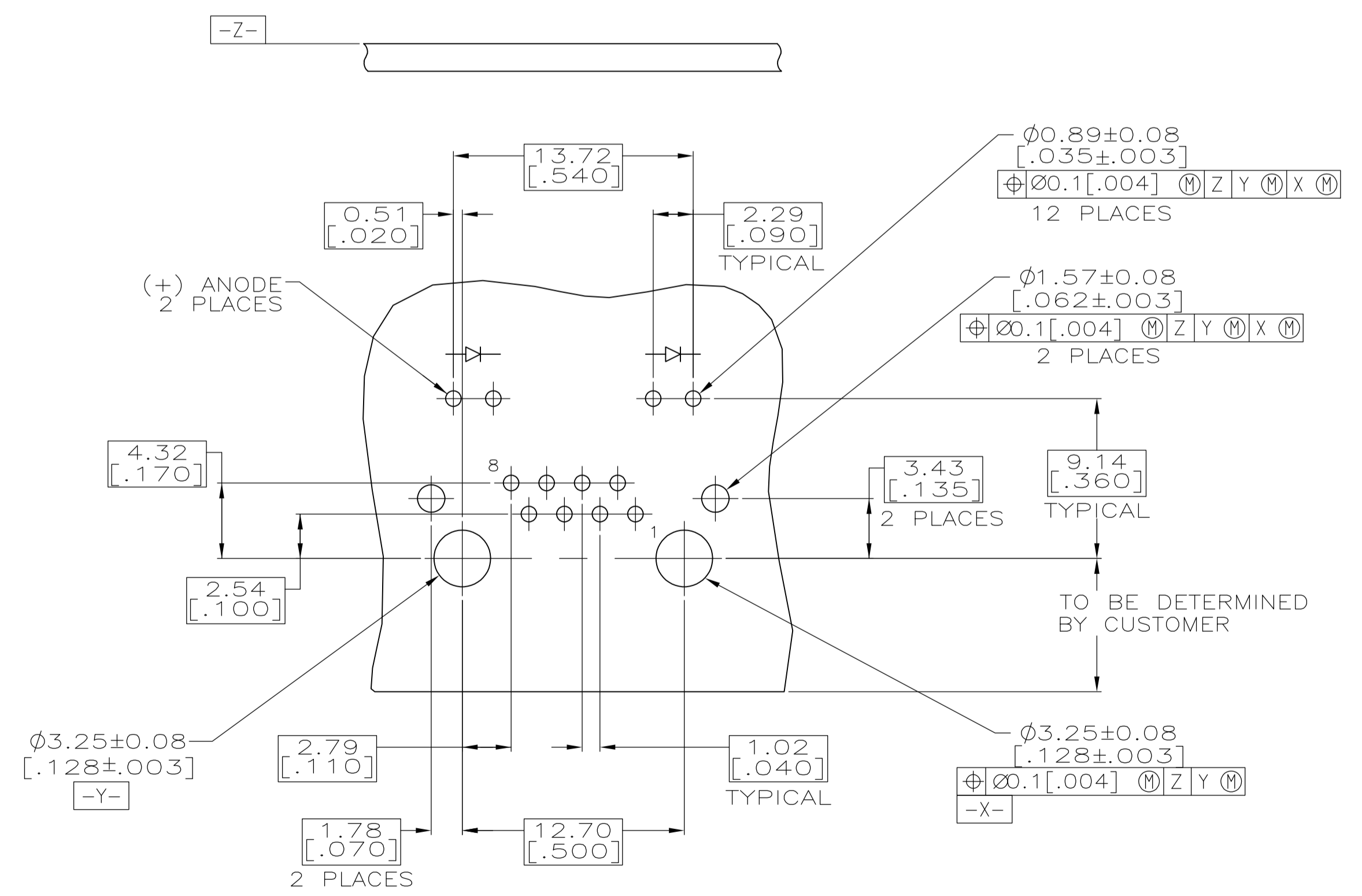


- △ MATERIAL:  
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.  
 TERMINALS - 0.36 THICK PHOS BRONZE PLATED WITH 3.81 μm MIN THICK MATTE TIN IN SOLDER AREA. 1.27 μm [.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27 μm MIN THICK NICKEL.  
 SHIELD - 0.196 THICK COPPER ZINC ALLOY PREPLATED WITH 1.27 μm MIN SATIN NICKEL WITH 2.03 μm MIN TIN POST DIPPED ON PCB GROUND TABS.  
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51 CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89 μm THICK Sn/Cu OVER 2.03 μm THICK Ag OVER 1.02 μm THICK Cu OVER 3.56 μm THICK Ni OVER 1.02 μm THICK Cu UNDERPLATE
2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.
- △ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
- △ SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.
6. THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.



LED CURRENT DIAGRAM  
1116075-7 ONLY



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT  
(COMPONENT SIDE)

INDICATOR COLOR	POSITION 2	POSITION 1	PART NUMBER
ORANGE/GREEN	ORANGE/GREEN		6116075-7
YELLOW	YELLOW		6116075-6
GREEN	GREEN		6116075-5
GREEN	YELLOW		6116075-4
YELLOW	-		6116075-3
-	GREEN		6116075-2
YELLOW	GREEN		6116075-1

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm	TOLERANCES UNLESS OTHERWISE SPECIFIED:	DIN T. SPRINKLE/L.A. MAYER 30APR2005	CHK J. WESTMAN 30APR2005	APVD S. FLICKINGER 30APR2005	NAME
0 PLC ± -	1 PLC ± -	2 PLC ± 0.25[.01]	3 PLC ± 0.13[.005]	4 PLC ± -	ANGLES ± -
MATERIAL SEE NOTE 1	FINISH SEE NOTE 1	WEIGHT	SIZE 108-1163-4	CAGE CODE	DRAWING NO. 00779
CUSTOMER DRAWING		SCALE 4:1	SHEET 1 of 1	REV A1	RESTRICTED TO

STE TE Connectivity  
 INVERTED MODULAR JACK ASSEMBLY, 1X1, SHIELDED, LED